

## Surface Mount Schottky Barrier Rectifier

Reverse Voltage -20V to 200V

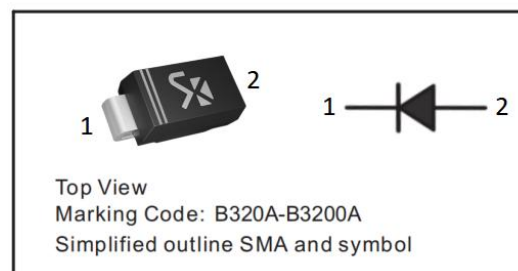
Forward Current -3.0A

### Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

### PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



## Absolute Maximum Ratings and Electrical characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20%

Parameter		Symbol	B320 AG	B340 AG	B360 AG	B380 AG	B3100 AG	B3120 AG	B3150 AG	B3200 AG	Unit
Maximum Repetitive Peak Reverse Voltage		V <sub>RRM</sub>	20	40	60	80	100	120	150	200	V
Maximum RMS Voltage		V <sub>RMS</sub>	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage		V <sub>DC</sub>	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current		I <sub>F(AV)</sub>	3.0								A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed On Rated Load (JEDEC method)		I <sub>FSM</sub>	80								A
Peak Forward Surge Current, 1.0ms Single Half Sine-wave Superimposed On Rated Load (JEDEC method)		I <sub>FSM</sub>	160								A
I²t Rating for fusing (3ms≤8.3ms)		I²t	26.5								A²S
Max Instantaneous Forward Voltage at 3A		V <sub>F</sub>	0.55		0.70	0.85		0.95			V
Maximum DC Reverse Current at Rated DC Reverse Voltage	T <sub>a</sub> = 25°C	I <sub>R</sub>	0.5			0.3					mA
	T <sub>a</sub> =100°C		5			3					
Typical Junction Capacitance <sup>(1)</sup>		C <sub>j</sub>	135		107	83		68		50	pF
Typical Thermal Resistance <sup>(2)</sup>		R <sub>θJA</sub>	100								°C/W
		R <sub>θJC</sub>	20								
		R <sub>θJL</sub>	25								
Operating Junction Temperature		T <sub>j</sub>	-55~+125								°C
Storage Temperature Range		T <sub>stg</sub>	-55~+150								°C

(1) Measured at 1MHz and applied reverse voltage of 4V D.C

(2) P.C.B. mounted with 0.2"x0.2" (5x5mm) copper pad areas

## Typical Characteristics

Fig.1 Forward Current Derating Curve

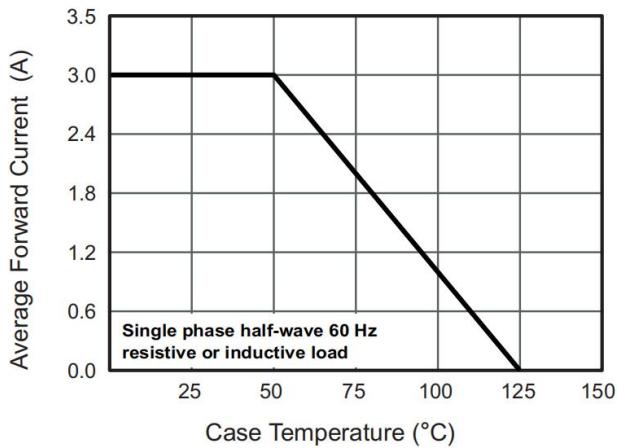


Fig.2 Typical Reverse Characteristics

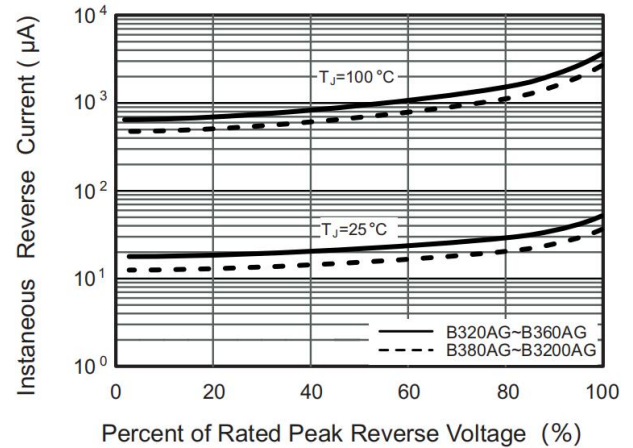


Fig.3 Typical Forward Characteristic

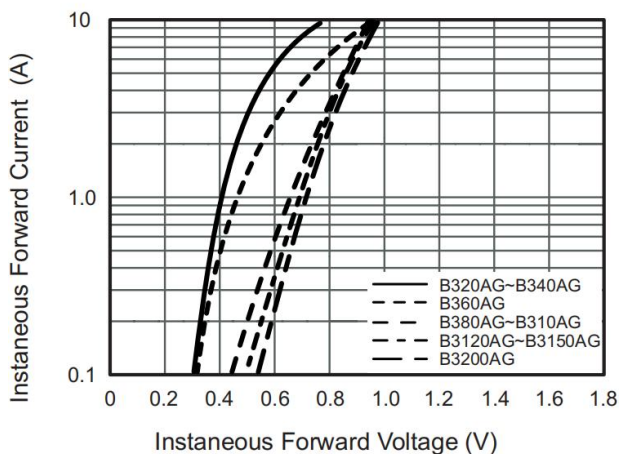


Fig.4 Typical Junction Capacitance

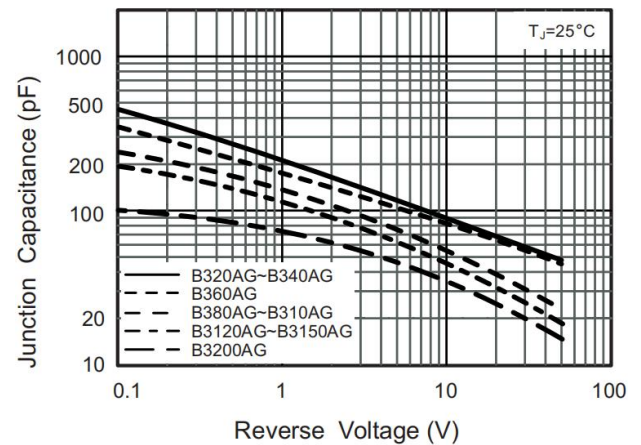
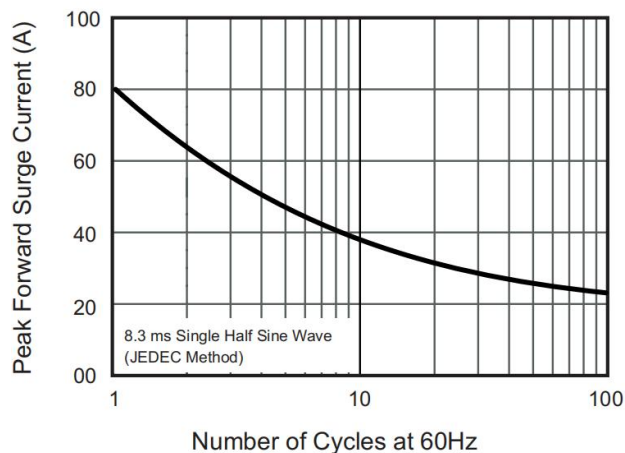


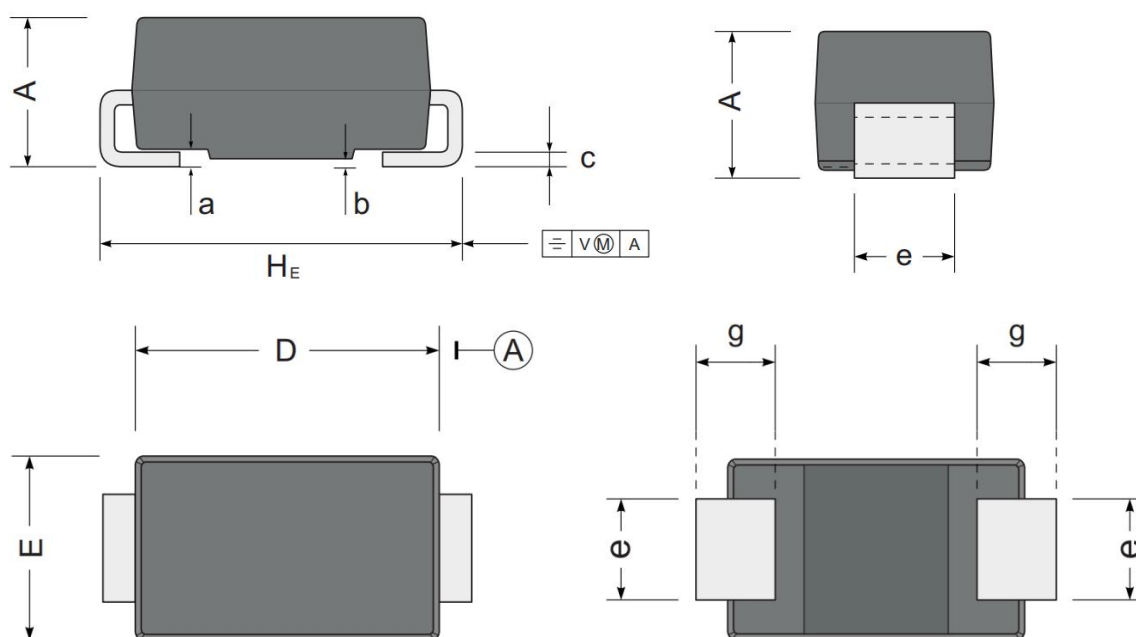
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



## Package Information

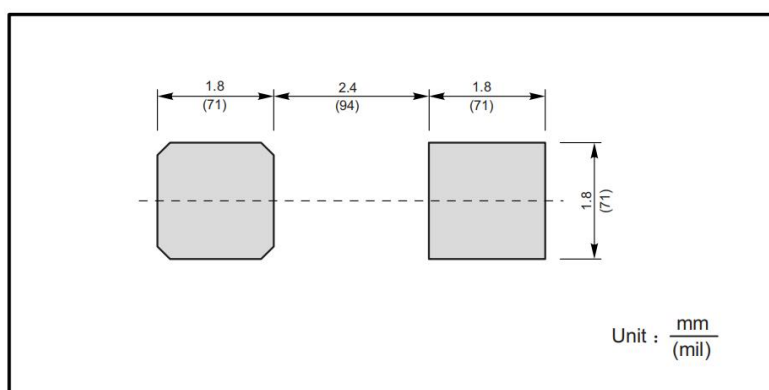
### SMA

### Dimensions in mm



UNIT		A	D	E	H <sub>E</sub>	c	e	g	b	a
mm	max	2.2	4.5	2.7	5.2	0.31	1.6	1.5	0.2	0.3
	min	1.9	4.0	2.3	4.7	0.15	1.3	0.9	0.05	
mil	max	87	181	106	205	12	63	59	7.9	12
	min	75	157	91	185	6	51	35	2	

### The recommended mounting pad size



## Shikues Disclaimer

### 1.Accuracy of Information and Right to Modify

The information provided in this document is for reference only. Shikues reserves the right to make changes to this document and to the specifications of the products described herein at any time, without prior notice, for the purpose of improving reliability, function, design, or for any other reason. It is the customer's responsibility to obtain and verify the latest product information and specifications before making any final design, procurement, or usage decisions.

### 2.No Warranty

Shikues makes no express or implied warranties, representations, or guarantees regarding the suitability of its products for any particular purpose.

Shikues assumes no liability for any assistance provided or for the design of customer products. All products are supplied "as is."

### 3.Intended Use and Limitation of Liability

The products described in this document are intended for use in general-purpose electronic devices. They are neither designed nor tested nor authorized for use in transportation equipment or applications requiring high reliability. Unless expressly authorized in writing by Shikues, these products must not be used as critical components in life-support systems or any applications where failure could directly pose a risk to human life (including, but not limited to, medical devices, transportation systems, aerospace equipment, nuclear facilities, and safety-critical systems).

Shikues assumes no responsibility or liability for any consequences arising from the use of its products in unauthorized or unintended applications.

Neither Shikues nor its representatives shall be held liable for any resulting damages.

### 4.Intellectual Property

This document does not grant any express or implied license—whether by estoppel, implication, or otherwise—to use any intellectual property rights of Shikues.